Title (en)

CONNECTION ARRANGEMENT OF AN ELECTRIC AND/OR ELECTRONIC COMPONENT

Title (de)

VERBINDUNGSANORDNUNG EINES ELEKTRISCHEN UND/ODER ELEKTRONISCHEN BAUELEMENTS

Title (fr)

SYSTÈME DE CONNEXION D'UN COMPOSANT ÉLECTRIQUE ET/OU ÉLECTRONIQUE

Publication

EP 2812912 A2 20141217 (DE)

Application

EP 13702765 A 20130125

Priority

- DE 102012201935 A 20120209
- EP 2013051400 W 20130125

Abstract (en)

[origin: WO2013117438A2] The connection arrangement (100, 200, 300, 400) comprises at least one electric and/or electronic component (1). The at least one electric and/or electronic component (10) has at least one connection face (11), which is connected in a bonded manner to a join partner (40) by means of a connection layer (20). The connection layer (20) can for example be an adhesive, soldered, welded, sintered connection or another known connection that connects joining partners while forming a material connection. Furthermore, a reinforcement layer (30') is arranged adjacent to the connection layer (20) in a bonded manner. The reinforcement layer (30') has a higher modulus of elasticity than the connection layer (20). A particularly good protective effect is achieved if the reinforcement layer (30') is formed in a frame-like manner by an outer and an inner boundary (36, 35) and, at least with the outer boundary (36) thereof, encloses the connection face (11) of the at least one electric and/or electronic component (10).

IPC 8 full level

H01L 21/60 (2006.01)

CPC (source: CN EP US)

B23K 1/0008 (2013.01 - US); **B23K 1/19** (2013.01 - US); **B23K 35/025** (2013.01 - EP US); **B23K 35/3006** (2013.01 - EP US); **H01L 24/27** (2013.01 - CN EP US); **H01L 24/29** (2013.01 - CN EP US); **H01L 24/30** (2013.01 - EP US); **H01L 24/32** (2013.01 - CN EP US); **H01L 24/83** (2013.01 - CN EP US); B23K 2103/08 (2018.08 - EP US); B23K 2103/56 (2018.08 - EP US); H01L 2224/26125 (2013.01 - EP US); H01L 2224/26155 (2013.01 - EP US); H01L 2224/27013 (2013.01 - CN EP US); H01L 2224/2732 (2013.01 - CN EP US); H01L 2224/29016 (2013.01 - US); H01L 2224/29076 (2013.01 - EP US); H01L 2224/29105 (2013.01 - US); H01L 2224/29111 (2013.01 - US); H01L 2224/29113 (2013.01 - US); H01L 2224/29118 (2013.01 - US); H01L 2224/29124 (2013.01 - US); H01L 2224/29139 (2013.01 - US); H01L 2224/29147 (2013.01 - US); H01L 2224/30515 (2013.01 - EP US); H01L 2224/32013 (2013.01 - CN EP US); H01L 2224/32014 (2013.01 - CN EP US); H01L 2224/32225 (2013.01 - CN EP US); H01L 2224/32245 (2013.01 - CN EP US); H01L 2224/32507 (2013.01 - CN EP US); H01L 2224/83101 (2013.01 - CN EP US); H01L 2224/83192 (2013.01 - CN EP US); H01L 2224/83194 (2013.01 - CN EP US); H01L 2224/83801 (2013.01 - CN EP US); H01L 2224/83825 (2013.01 - CN EP US); H01L 2224/8384 (2013.01 - CN EP US); H01L 2224/8392 (2013.01 - CN EP US); H01L 2224/83948 (2013.01 - CN EP US); H01L 2224/83951 (2013.01 - CN EP US); H01L 2924/01013 (2013.01 - US); H01L 2924/0103 (2013.01 - US); H01L 2924/01031 (2013.01 - US); H01L 2924/0105 (2013.01 - US); H01L 2924/01083 (2013.01 - US); H01L 2924/01327 (2013.01 - CN EP US); H01L 2924/10253 (2013.01 - CN EP US); H01L 2924/1203 (2013.01 - CN EP US); H01L 2924/1304 (2013.01 - CN EP US); H01L 2924/1305 (2013.01 - CN EP US); H01L 2924/13055 (2013.01 - CN EP US); H01L 2924/13091 (2013.01 - CN EP US); H01L 2924/14 (2013.01 - CN EP US); H01L 2924/15747 (2013.01 - EP US); H01L 2924/3512 (2013.01 - CN EP US)

C-Set (source: CN EP US)

CN

1. H01L 2924/01327 + H01L 2924/00
2. H01L 2224/83192 + H01L 2224/32245 + H01L 2924/00
3. H01L 2224/83192 + H01L 2224/32225 + H01L 2924/00
4. H01L 2224/83192 + H01L 2224/83101 + H01L 2924/00

EP US

1. H01L 2924/01327 + H01L 2924/00
2. H01L 2224/83192 + H01L 2224/32245 + H01L 2924/00
3. H01L 2224/83192 + H01L 2224/32225 + H01L 2924/00
4. H01L 2224/83192 + H01L 2224/83101 + H01L 2924/00
5. H01L 2924/1305 + H01L 2924/00
6. H01L 2924/15747 + H01L 2924/00

Citation (examination)

- US 2011084384 A1 20110414 - SAKATA KENJI [JP], et al
- EP 1039526 A2 20000927 - FORD MOTOR CO [US]
- JP S5244566 A 19770407 - MITSUBISHI ELECTRIC CORP
- JP 2007109834 A 20070426 - FUJI ELECTRIC HOLDINGS
- JP S5966131 A 19840414 - NIPPON ELECTRIC CO
- See also references of WO 2013117438A2

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

DE 102012201935 A1 20130814; CN 104094387 A 20141008; CN 104094387 B 20170808; EP 2812912 A2 20141217; US 2015014865 A1 20150115; US 2016064350 A1 20160303; US 9177934 B2 20151103; WO 2013117438 A2 20130815; WO 2013117438 A3 20131003

DOCDB simple family (application)

DE 102012201935 A 20120209; CN 201380008409 A 20130125; EP 13702765 A 20130125; EP 2013051400 W 20130125; US 201314377895 A 20130125; US 201514834569 A 20150825